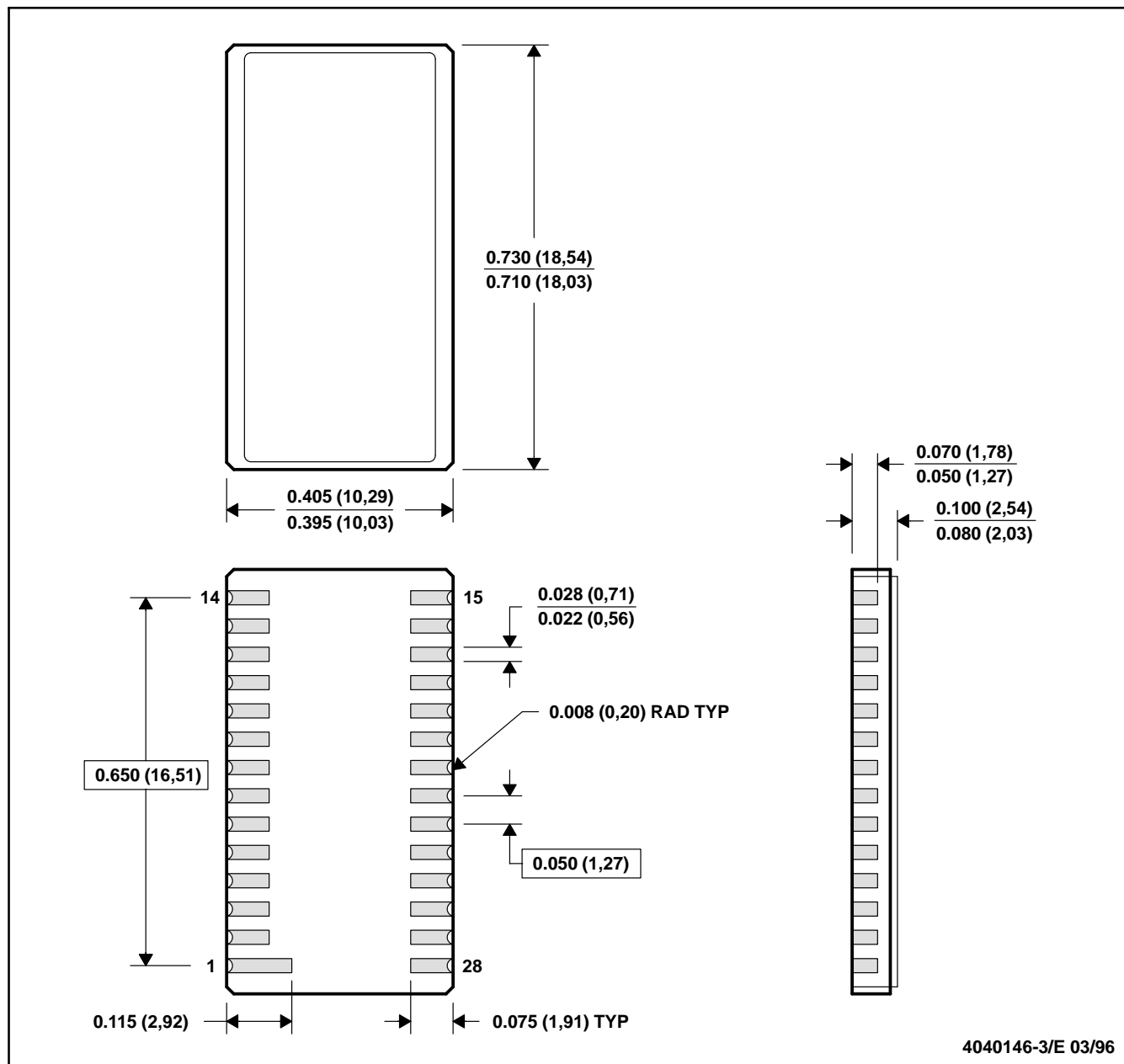


HM (R-CDCC-N28)

LEADLESS CERAMIC CHIP CARRIER



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. The terminals will be gold plated.

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